imall

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T-1 3/4 (5mm) BI-COLOR INDICATOR LAMP

Part Number: WP59GYC

Green Yellow

Features

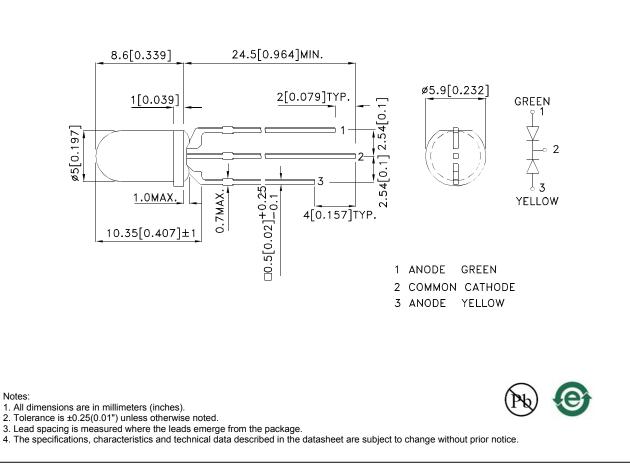
- Uniform light output.
- Low power consumption.
- 3 leads with one common lead.
- Long life-solid state reliability.
- RoHS compliant.

Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions



SPEC NO: DSAF2652 APPROVED: WYNEC REV NO: V.5B CHECKED: Allen Liu DATE: FEB/15/2013 DRAWN: Y.Liu PAGE: 1 OF 7 ERP: 1101005799

Selection Guide lv (mcd) [2] Viewing @ 20mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. Green (GaP) 50 120 WP59GYC 24° Water Clear Yellow (GaAsP/GaP) 40 80

Notes:

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green Yellow	565 590		nm	IF=20mA
λD [1]	Dominant Wavelength	Green Yellow	568 588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green Yellow	30 35		nm	IF=20mA
С	Capacitance	Green Yellow	15 20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green Yellow	2.2 2.1	2.5 2.5	V	IF=20mA
lr	Reverse Current	Green Yellow		10 10	uA	VR = 5V

Notes:

Wavelength: +/-1nm.
Forward Voltage: +/-0.1V.
Wavelength value is traceable to the CIE127-2007 compliant national standards.

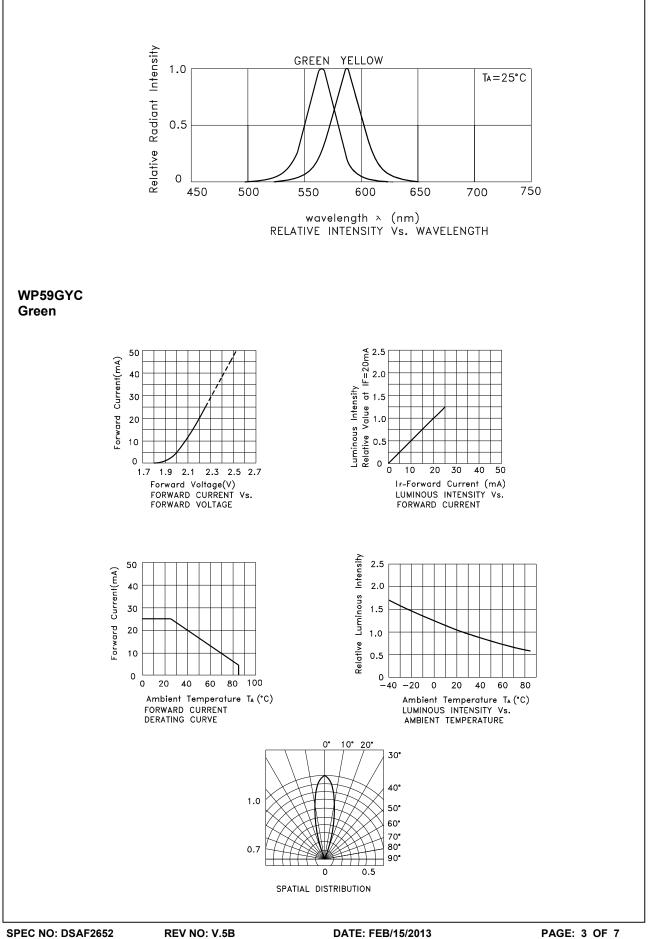
Absolute Maximum Ratings at TA=25°C

Parameter	Green	Yellow	Units		
Power dissipation	62.5	75	mW		
DC Forward Current	orward Current 25		mA		
Peak Forward Current [1]	140	140	mA		
Reverse Voltage		V			
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				
Notos:					

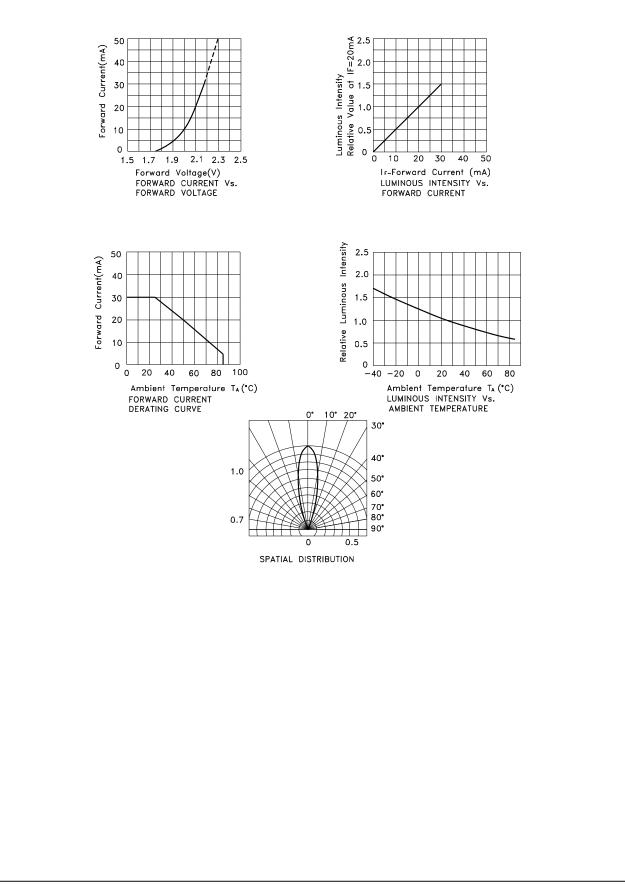
Notes

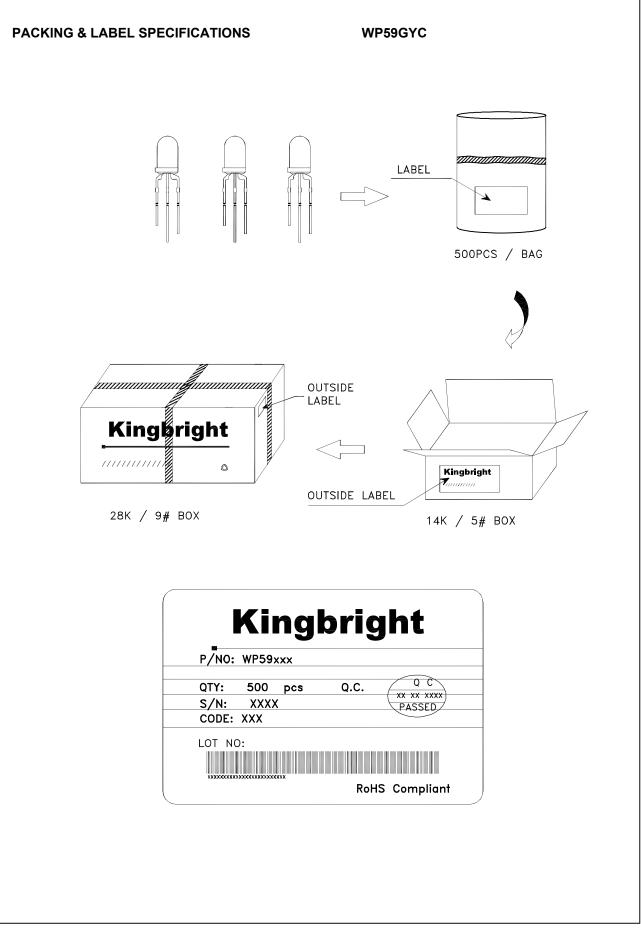
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.
3. 5mm below package base.



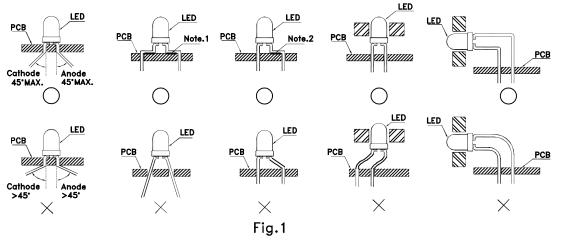
Yellow





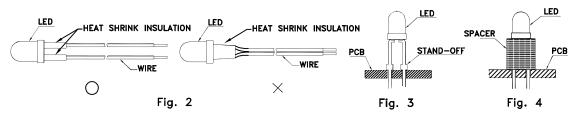
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

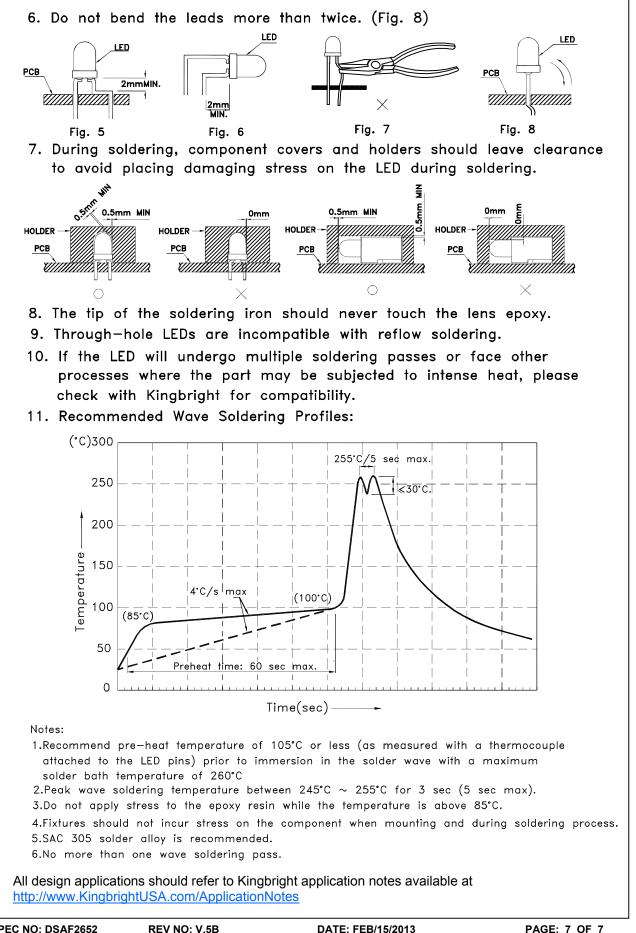


" \bigcirc " Correct mounting method "imes" Incorrect mounting method

- 2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



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